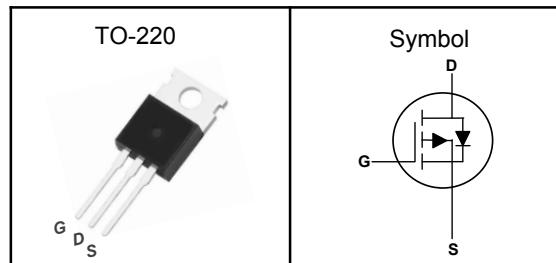


P-Channel Enhancement Mode MOSFET

Features

- Low Rdson for low conduction loss
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

Pin Description



Applications

- Power Management in Desktop Computer
- DC/DC Converters

V _{DSS}	-60	V
R _{D(S(ON)-Typ)}	8.0	mΩ
I _D	-100	A

Absolute Maximum Ratings (T_C=25°C, Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
V _{DSS}	Drain-Source Voltage	-60	V
V _{GSS}	Gate-Source Voltage	±20	V
T _J	Maximum Junction Temperature	-55 to 150	°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
I _{DM} ⁽¹⁾	Pulse Drain Current Tested	-300	A
I _D	Continuous Drain Current	-100	A
P _D	Maximum Power Dissipation	142	W
E _{AS}	Single Pulse Avalanche Energy	650	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
R _{θJA} ⁽²⁾	Thermal Resistance-Junction to Ambient	60	°C/W
R _{θJC}	Thermal Resistance Junction-Case	0.88	°C/W

Note (1) : Max. current is limited by bonding wire.

Note (2) : UIS tested and pulse width are limited by maximum junction temperature 150°C.

Note (3) : Surface Mounted on 1in² FR-4 board with 1oz.

P-Channel Enhancement Mode MOSFET

Electrical Characteristics ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=-250\mu\text{A}$	-60	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-60\text{V}$, $V_{\text{GS}}=0\text{V}$	---	---	-1	μA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_{\text{D}}=-250\mu\text{A}$	-1.0	---	-2.5	V
I_{GSS}	Gate Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$R_{\text{DS(ON)}}$	Drain-Source On-state Resistance	$V_{\text{GS}}=-10\text{V}$, $I_{\text{D}}=-20\text{A}$	---	8.0	10	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-15\text{A}$	---	10	12	
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$, $I_{\text{D}}=-20\text{A}$	---	18	---	S
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=-25\text{V}$, Freq.=1MHz	---	8620	---	pF
C_{oss}	Output Capacitance		---	486	---	
C_{rss}	Reverse Transfer Capacitance		---	288	---	
$T_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=-48\text{V}$, $V_{\text{GS}}=-10\text{V}$, $R_{\text{G}}=6\Omega$, $I_{\text{D}}=-1\text{A}$	---	70	---	nS
T_{r}	Turn-on Rise Time		---	205	---	
$T_{\text{d(off)}}$	Turn-off Delay Time		---	402	---	
T_{f}	Turn-off Fall Time		---	402	---	
Q_{g}	Total Gate Charge	$V_{\text{DS}}=-48\text{V}$, $V_{\text{GS}}=-10\text{V}$, $I_{\text{D}}=-5\text{A}$	---	141	---	nC
Q_{gs}	Gate-Source Charge		---	71	---	
Q_{gd}	Gate-Drain Charge		---	28	---	
Source-Drain Characteristics						
$V_{\text{SD}}^{④}$	Diode Forward Voltage	$I_{\text{S}}=-1\text{A}$, $V_{\text{GS}}=0\text{V}$	---	---	-1.2	V

Note ④: Pulse test (pulse width 300us, duty cycle 2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

P-Channel Enhancement Mode MOSFET

Typical Characteristics

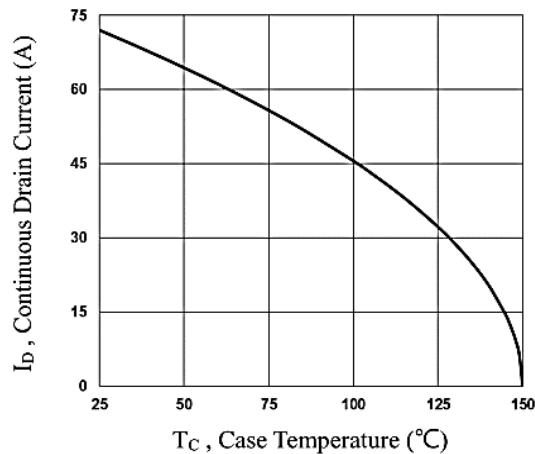


Fig.1 Typical Output Characteristics

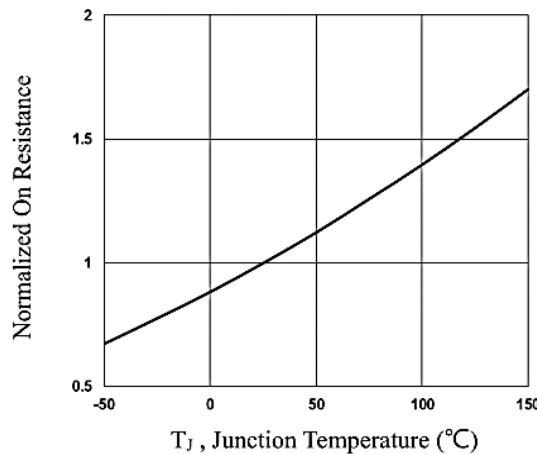


Fig.2 Normalized RDS(on) vs. TJ

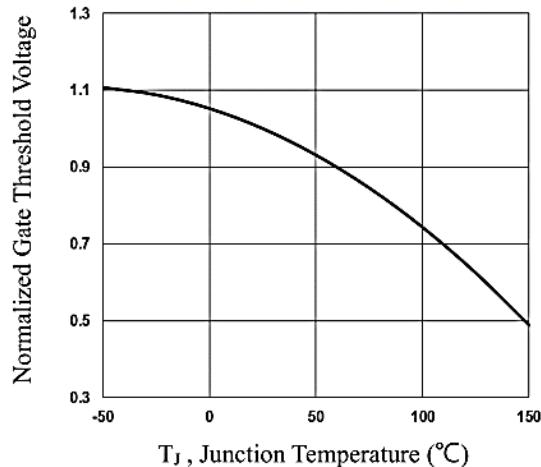


Fig.3 Normalized RDS(on) vs. TJ

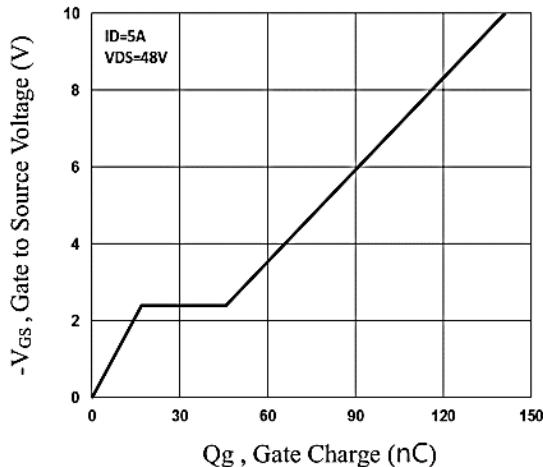


Fig.4 Normalized V_{th} vs. TJ

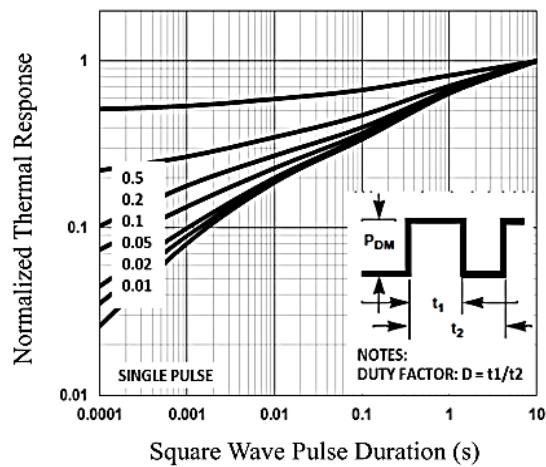


Fig.5 Normalized Transient Impedance

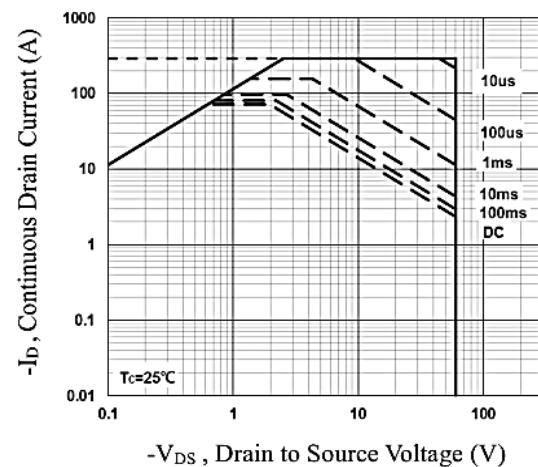
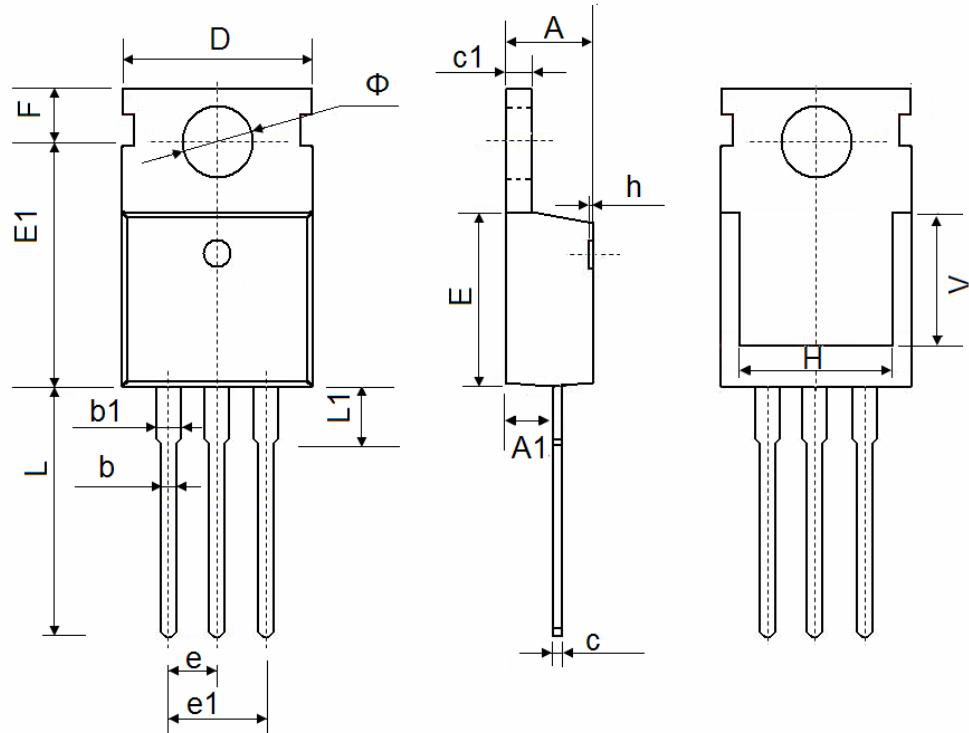


Fig.6 Maximum Safe Operation Area

P-Channel Enhancement Mode MOSFET

TO-220 Package Outline Data



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	4.350	4.650
A1	2.250	2.550
b	0.710	0.910
b1	1.170	1.400
c	0.330	0.650
c1	1.200	1.400
D	9.910	10.250
E	8.9500	9.750
E1	12.650	12.950
e	2.540 TYP.	
e1	4.980	5.180
F	2.650	2.950
H	7.900	8.100
h	0.000	0.300
L	12.700	13.500
L1	2.850	3.250
V	7.500 REF.	
Φ	3.400	3.800